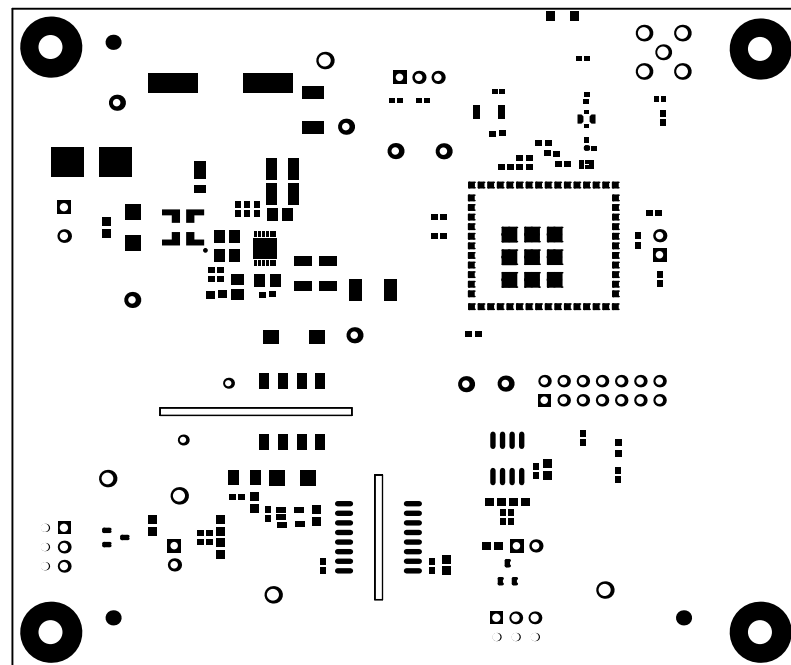
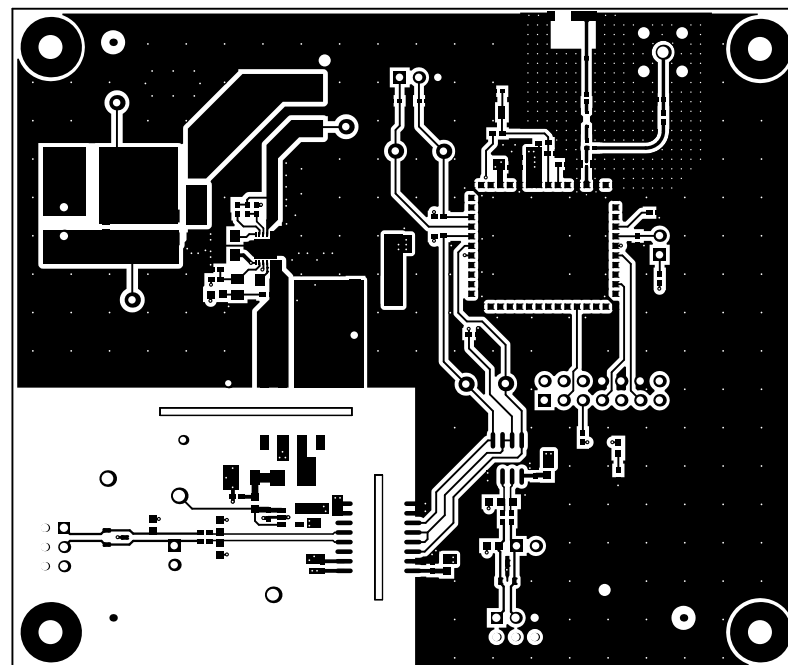


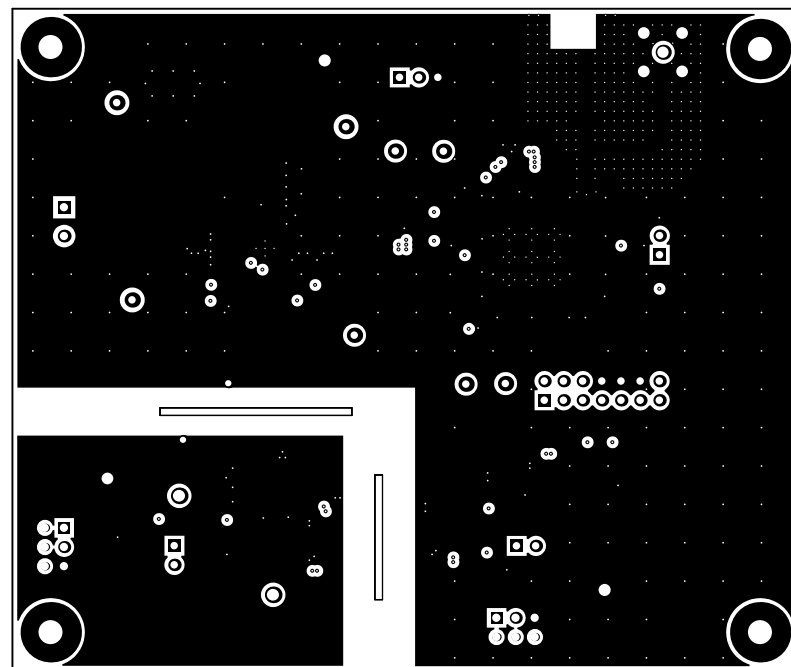
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-00485		
PLOT NAME = Top Overlay	GENERATED : 6/16/2015	1:53:28 PM	TEXAS INSTRUMENTS



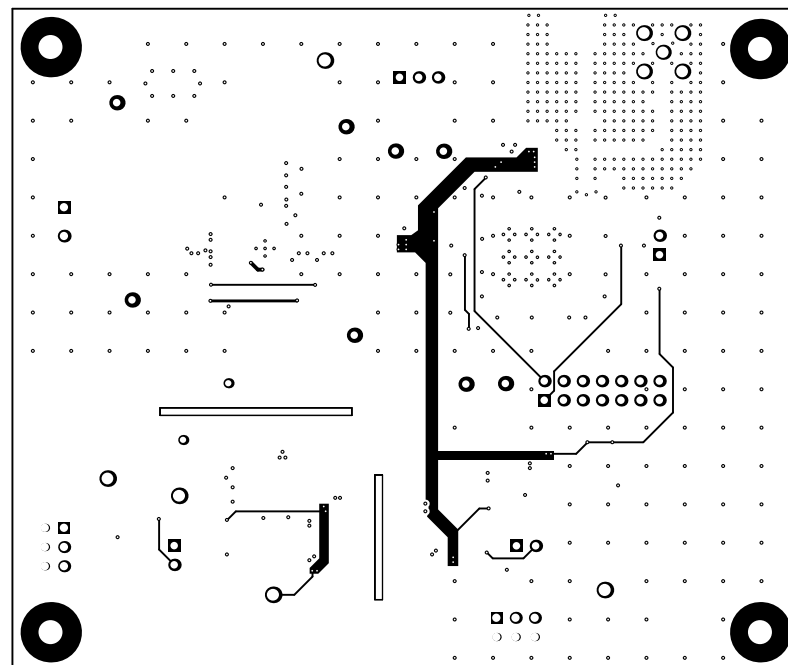
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-00485		
PLOT NAME = Top Solder Mask	GENERATED : 6/16/2015	1:53:29 PM	TEXAS INSTRUMENTS



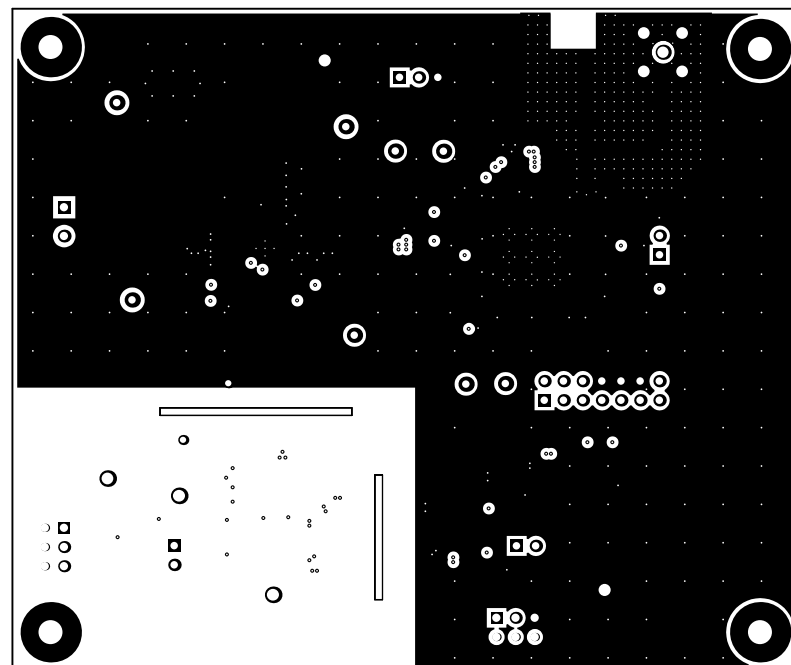
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-00485		
PLOT NAME = Top Layer	GENERATED : 6/16/2015	1:53:31 PM	TEXAS INSTRUMENTS



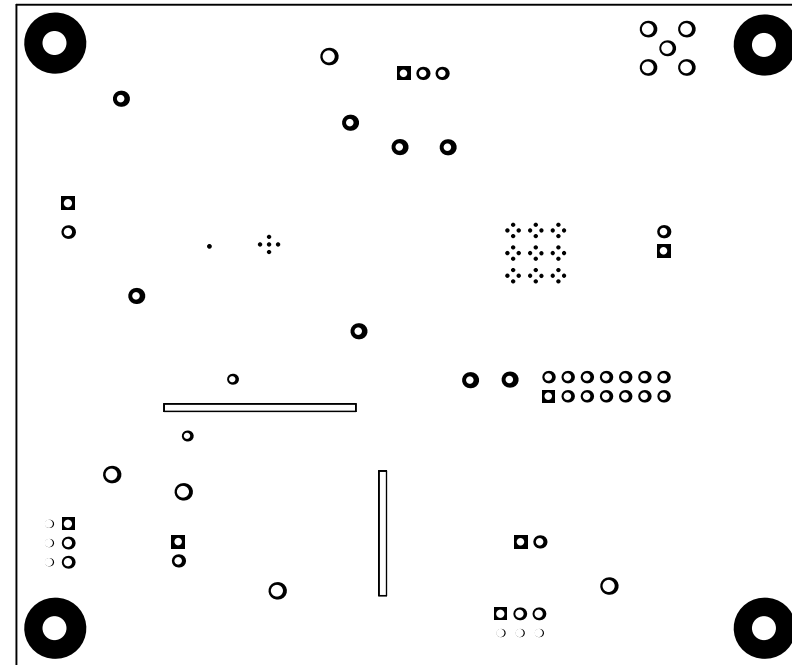
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: TIDA-00485		
PLOT NAME = Signal Layer 1	GENERATED : 6/16/2015	1:53:34 PM	TEXAS INSTRUMENTS



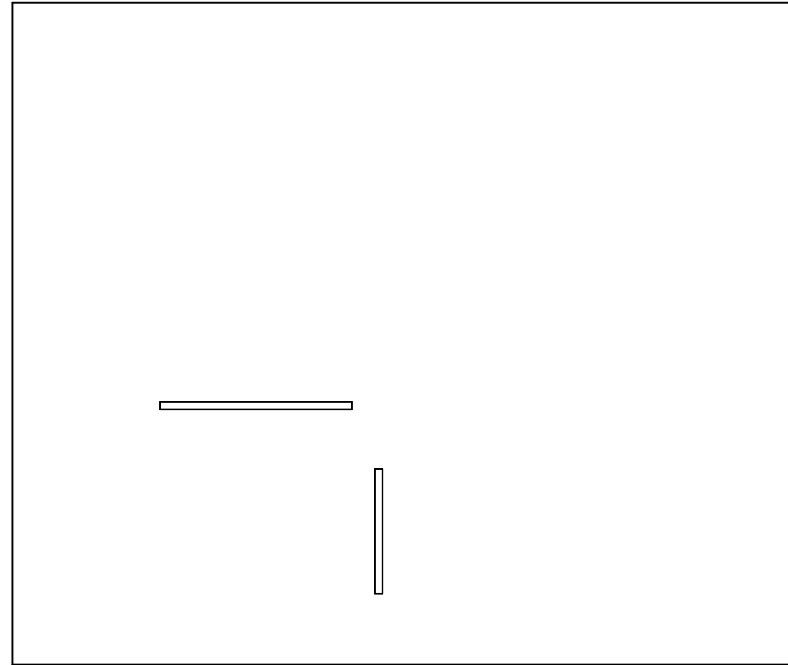
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: TIDA-00485		
PLOT NAME = Signal Layer 2	GENERATED : 6/16/2015 1:53:36 PM	TEXAS INSTRUMENTS	



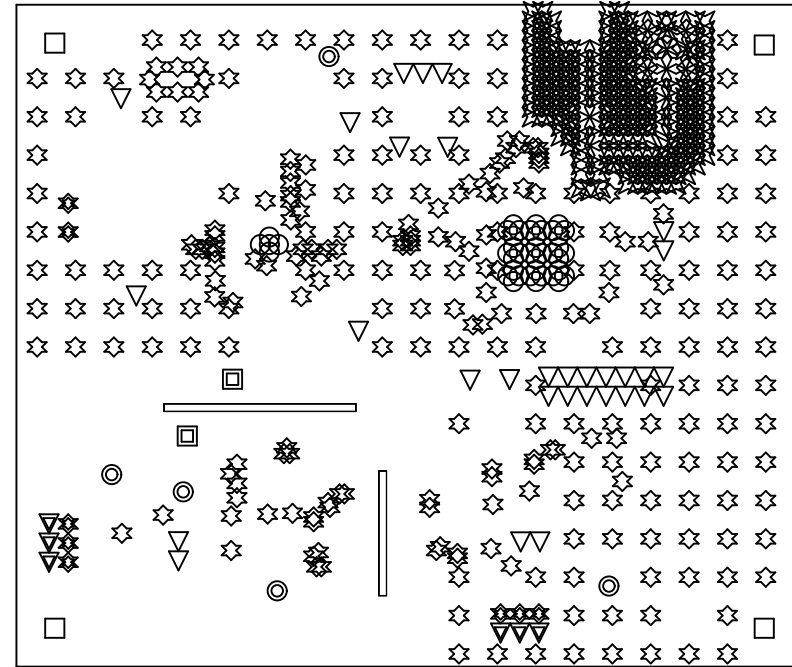
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-00485		
PLOT NAME = Bottom Layer	GENERATED : 6/16/2015	1:53:39 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-00485		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/16/2015 1:53:42 PM	TEXAS INSTRUMENTS	

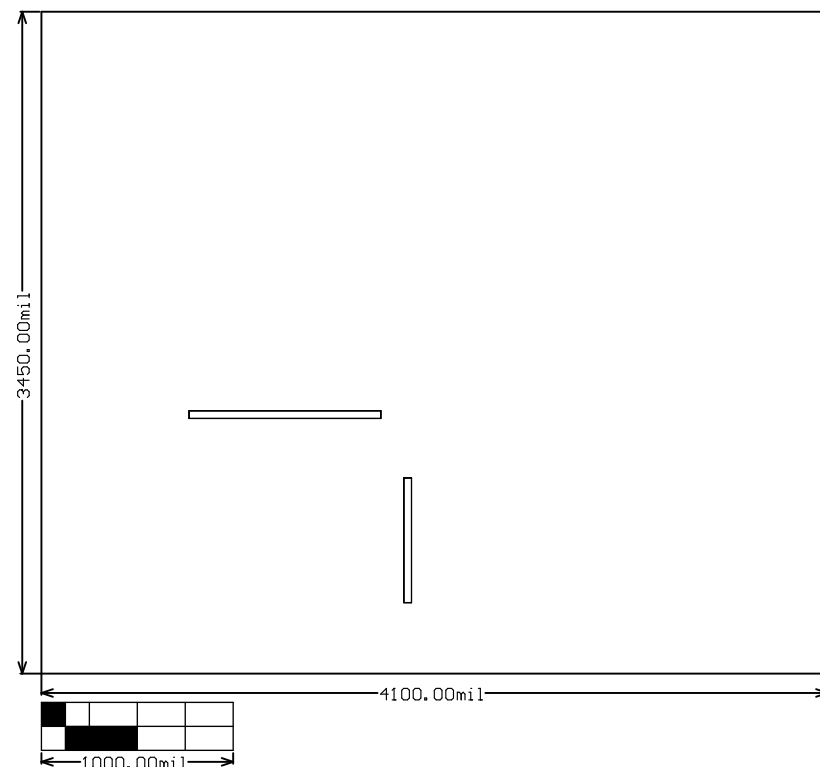


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-00485		
PLOT NAME = Bottom Overlay	GENERATED : 6/16/2015 1:53:45 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▼	6	43.31mil (1.100mm)	NPTH	Round
○	41	7.87mil (0.200mm)	PTH	Round
⊗	233	8.00mil (0.203mm)	PTH	Round
☆	277	10.00mil (0.254mm)	PTH	Round
■	2	33.46mil (0.850mm)	PTH	Round
▽	31	40.00mil (1.016mm)	PTH	Round
✱	8	43.31mil (1.100mm)	PTH	Round
⊗	1	59.06mil (1.500mm)	PTH	Round
◇	4	62.99mil (1.600mm)	PTH	Round
●	5	63.00mil (1.600mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
	612 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-00485		
PLOT NAME = Drill Drawing	GENERATED : 6/16/2015	1:53:48 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: ISE4037	REV: E3	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-00485		
PLOT NAME = Board Dimensions	GENERATED : 6/16/2015 1:53:52 PM	TEXAS INSTRUMENTS	

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